

# Cryogenic Pulsating Heat Pipes Update and Direction

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## Structure

- Introduction to the topic
- Unique features of cryogenic PHPs recent reports
- Modeling a helium PHP using Fluent CFD
  - Scope & specifications
  - Mass balance
    - Properties
    - Phase change
  - Model output
  - Influence of copper plate
  - On-going activities

# Introduction

# What is a Pulsating Heat Pipe (PHP)?



• First developed in 1990: Akachi, 5<sup>th</sup> Intl. Heat Pipe Symposium

- Multiple loops of capillary tubing (no wicking structure)
- Partially filled with heat transfer fluid – alternating liquid slugs and vapor plugs
- Oscillatory and circulatory motions effectively transfer heat from evaporator (hot) end to condenser (cold) end
- World wide interest for room temperature applications
- •Cryogenic attention since 2010

Khandekar, S., 2004, "Thermo-hydrodynamics of Closed Loop Pulsating Heat Pipes," Institut fur Kernenergetik und Energiesysteme der Universitat Stuttgart Recent Findings with Cryogenic PHPs

#### Continued Operation in Helium's Supercritical Region



UW-Madison: 2017. Fonseca PhD Thesis Similar behavior reported by: TIPC-CAS, 2018. Li, Li, Xu, *Cryogenics* **96**, pp. 159-165

#### Adiabatic-Length-Independent Conductance (Helium)



#### Dependence of Maximum Heat Transfer on A<sub>flow</sub> and Orientation (Neon)



# Modeling a Helium PHP via FLUENT

# **Objectives**

- Match model results to experimental data
- Gain insight regarding the internal flow characteristics and associated thermal performance
- Challenges & Learning:
  - Number of nodes as size increases: match full scale results: UW-Madison 21 turns 500 mm, TIPC-CAS 8 turns 200 mm.
  - Mass balance
  - Properties helium vapor is NOT an ideal gas (UDF)
  - Length independent conductance unidirectional flow?
  - Include copper plate on evaporator / condenser
  - How much detail is needed: film layer?

#### Geometry of Modeled PHPs

- Tube diameter: 0.5 mm
- Number of turns: 2, 5,10, 21, and 24 turns
- Length: 50 mm, 200 mm, and 500 mm
- Bend diameter: 10 mm
- Evaporation length: 30 mm, and 50 mm
  - Uniform Heat Flux BC (remember this)
- Condenser length: 90 mm, and 50 mm
  - Uniform Temperature BC
- Typically model the condenser walls as fixed temperature and evaporator walls as fixed heat flux. Not exactly the same BC's as experiments but we assumed this was a good starting point.

# **Ansys Fluent Model**

#### Fluid Model

- Two phase: VOF method
- Viscous model: Laminar
- Mass Transfer Model: Lee Model

#### Numerical method:

- Pressure-velocity coupling: PISO
- Gradient: least square cell based
- Pressure: body forced weighted
- Density: second order upwind
- Momentum: Quick
- Volume fraction: geo-reconstruct
- Energy: first order upwind
- Transient: first order implicit

# High Performance Computing(HPC) system

Setup:

- Using 128 CPUs in the HPC system
- RAM/core=4 GB
- vs: Desktop:4 CPU with RAM/core=4GB

Running time:

- Takes a day on HPC to run 12 second simulation time for 10 turns 500 mm (This simulation would take more than a month on a desktop machine)
- Running times linearly increasing with increasing mesh size(geometry size) in each dimension and in time step size.

Mesh number examples:

- 2turn 50mm: 24190
- 2turn 500mm:196762
- 24turn 200mm:479407

## Mass Balance

Influencing factors:

- Properties
- Lee model frequency
- Time step
- Iterations per time step
- Initial guess of T<sub>evap</sub>



### Helium Fluid Properties

Properties defined in the range from 3 Kelvin up to 20 Kelvin

**Vapor:** Using user defined functions (UDF)

- conductivity and viscosity: piecewise polynomial
- Density, enthalpy, and heat capacity: functions of both temperature and pressure

**Liquid:** all properties use piecewise polynomial function along the saturation line

#### Lee model

The liquid-vapor mass transfer (evaporation and condensation) is governed by the vapor transport equation.

$$\frac{1}{\rho_{\rm v}} \left[ \frac{\partial}{\partial t} (\alpha_{\rm v} \rho_{\rm v}) + \nabla \cdot (\alpha_{\rm v} \rho_{\rm v} v) = \mathscr{S}_{\alpha_{\rm v}} + \dot{m}_{\rm v} - \dot{m}_{\rm vl} \right]$$

$$\begin{cases} \text{If } T_l > T_{\text{sat}}(\text{evaporation}) \\ \dot{m}_{lv} = \text{coeff}_e \alpha_l \rho_l \frac{T_l - T_{\text{sat}}}{T_{\text{sat}}} \\ \text{If } T_v < T_{\text{sat}}(\text{condensation}) \\ \dot{m}_{vl} = \text{coeff}_c \alpha_v \rho_v \frac{T_{\text{sat}} - T_v}{T_{\text{sat}}} \end{cases}$$

	Lee Model
Evaporation Fre	quency
0.1	
Condensation Fr	equency
0.1	
Saturation Temp constant	erature (k) ▼ Edit
constant	▼] Edit
19.4	== <u></u> == <u></u> == <u></u> == <u></u> == <u></u> = <u>=</u> <u>=</u> <u>=</u> <u>=</u> <u>=</u> <u>=</u>
13.4	

- Saturation temperature is set as a function of pressure
- Evaporation frequency :1
- Condensation frequency:50
- Frequency ratio:
  - Successful values: 1-50,1-150,10-10,10-50,10-500
  - Influenced by: heat flux,  $T_{condenser}$ ,  $A_{evaporator}$  /  $A_{condenser}$

### Visualization of inside of PHP















#### Time dependent plot



Oscillation of temperature, heat flux, velocity are observed

#### **Observations**

- We get oscillatory motion at low heat flux
- Circulation at high heat flux.
- Reversals of predominate flow direction
- Bubbles growing in the evaporator and shrinking in the condenser
- Changes in the number of bubbles in the PHP with time.
- However...

#### **Experimental data**



Figure 5-1: Ramping process, Labview snapshot

Data from our experiments at UW-Madison

Temperature profile slowly climbs up and then becomes steady

Very small temperature oscillation

30 minutes per run Approximately 3-5 minutes for the transient.

The average delta T between condenser and evaporator matches the simulation for the same heater input power.

### With plate vs no plate

Adding heat flux on the back of the plate vs adding heat flux directly on evaporator wall



Adding the plate 'damped' the temperature oscillations

## Heat capacity of the plate?

- Specific heat of copper at room temperature is 389.4 J/kg-K
- Specific heat of copper at 4 K is 0.09 J/kg-K. (4300 x smaller)
- The heat capacity of the copper is small and is not damping the oscillations.

# Heat capacity of the plate?

#### However:

 Thermal diffusivity of RRR 100 copper at room temperature is 1.14 E-4 m<sup>2</sup>/s.

This means the thermal wave propagation time for a 1 cm distance is 0.9 s. (90 s for 10 cm)

• Thermal diffusivity of RRR 100 copper at 4K is 0.71 m<sup>2</sup>/s.

This means the thermal wave propagation time for a 1 cm distance is 0.14 ms. (0.014 s (14 ms) for 10 cm)

#### At 10 second



vof

Wall heat flux

Wall heat flux is smaller when vapor is present While wall heat flux is bigger when the liquid is present

Boundary condition on wall: neither constant temperature/heat flux Changing heat flux on wall

#### 11 second



vof

Wall Heat flux

#### 12 second



vof

Wall Heat flux

# Future Work

- Include realistic boundary conditions. (Evaporator and condenser on copper plates with fixed heater power on evaporator plate and fixed temperature on condenser plate)
- Continue to validate model results with existing experimental data
- Investigate impact of fluid details on thermal behavior
- Once validation is complete, extend modeling to unique configurations such as,
  - Non-uniform orientation of components in gravity
  - Helium PHP operating above the critical pressure as has been demonstrated experimentally.

## Mesh size investigation



0.025mm radial node separation inflation layer (5)



0.05mm radial node separation inflation layer (10)



Capturing detail of liquid film layer Any change of thermal behavior?

### **Salient Observations**

- Cryogenic PHPs display unique behavior:
  - Performance persists into supercritical regime
  - Length independent conductance
  - Orientation sensitivity persists to large number of turns
- CFD modeling for helium PHP:
  - Use real gas properties
  - Lee model approximates mass transfer but requires attention
  - HPC necessary for full scale characterization
  - Copper's large thermal diffusivity at 4 K smooths temperatures

# Questions or Comments?